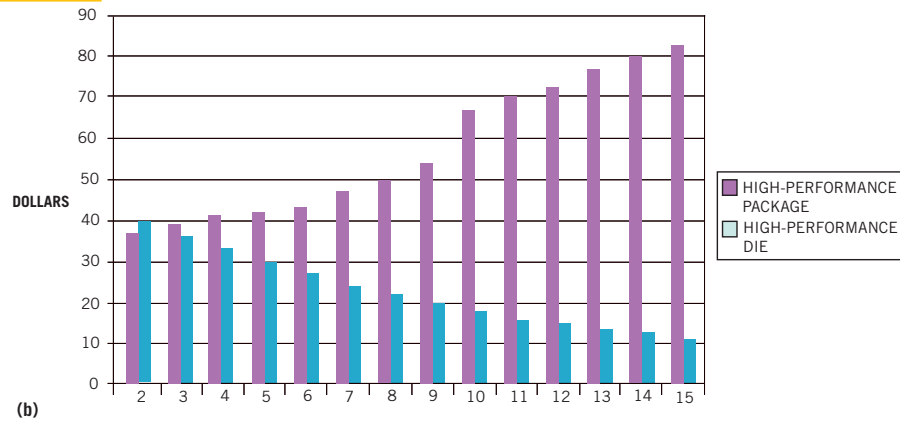


**Figure 1**



Industry projections suggest that packaging costs soon will outweigh silicon-die costs for both low- (a) and high-complexity (b) devices (courtesy *IEEE International Technology Roadmap for Semiconductors*).